

<b>Notice of References Cited</b>	Application/Control No. 10/598,124	Applicant(s)/Patent Under Reexamination SAKAMOTO ET AL.
	Examiner YOSHITOSHI TAKEUCHI	Art Unit 1726

**U.S. PATENT DOCUMENTS**

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
	A	US-			
	B	US-			
	C	US-			
	D	US-			
	E	US-			
	F	US-			
	G	US-			
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	K	US-			
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**FOREIGN PATENT DOCUMENTS**

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	N					
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	S					
	T					

**NON-PATENT DOCUMENTS**

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	Lee, Reflow Soldering Processes and Troubleshooting SMT, BGA, CSP and Flip Chip Technologies
	V	
	W	
	X	

\*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)  
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